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# Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







# **BLF7G22L-200**; BLF7G22LS-200 Power LDMOS transistor Rev. 5 — 1 September 2015

**AMPLEON** 

Product data sheet

## **Product profile**

## 1.1 General description

200 W LDMOS power transistor for base station applications at frequencies from 2110 MHz to 2170 MHz.

**Typical performance** Table 1.

Typical RF performance at  $T_{case} = 25$  °C in a common source class-AB production test circuit.

Mode of operation	f	I <sub>Dq</sub>	V <sub>DS</sub>	P <sub>L(AV)</sub>	Gp	$\eta_{D}$	ACPR
	(MHz)	(mA)	(V)	(W)	(dB)	(%)	(dBc)
2-carrier W-CDMA	2110 to 2170	1620	28	55	18.5	31	-31 <sup>[1]</sup>

<sup>[1]</sup> Test signal: 3GPP; test model 1; 64 DPCH; PAR = 8.4 dB at 0.01 % probability on CCDF; carrier spacing 5 MHz.

#### 1.2 Features and benefits

- Excellent ruggedness
- High efficiency
- Low R<sub>th</sub> providing excellent thermal stability
- Designed for low memory effects providing excellent pre-distortability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

## 1.3 Applications

RF power amplifiers for W-CDMA base stations and multi carrier applications in the 2110 MHz to 2170 MHz frequency range

## 2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
BLF7G22	L-200 (SOT502A)			
1	drain			,
2	gate			<u>,                                     </u>
3	source	<u>[1]</u>		2 —
				3 sym112
BLF7G22	LS-200 (SOT502B)			•
1	drain			
2	gate		3	,∟¹
3	source	<u>[1]</u>	2	2
				3
				sym112

<sup>[1]</sup> Connected to flange.

## 3. Ordering information

Table 3. Ordering information

Type number	Package								
	Name	Description	Version						
BLF7G22L-200	-	flanged LDMOST ceramic package; 2 mounting holes; 2 leads	SOT502A						
BLF7G22LS-200	-	earless flanged LDMOST ceramic package; 2 leads	SOT502B						

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage		-	65	V
$V_{GS}$	gate-source voltage		-0.5	+13	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	200	°C

## 5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
$R_{th(j-c)}$	thermal resistance from junction to case	$T_{case}$ = 80 °C; $P_{L}$ = 80 W (CW); $V_{DS}$ = 28 V; $I_{Dq}$ = 1620 mA	0.26	K/W

BLF7G22L-200\_7G22LS-200#5

## 6. Characteristics

Table 6. Characteristics

 $T_i = 25$  °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 1.5 \text{ mA}$	65	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	$V_{DS}$ = 10 V; $I_{D}$ = 150 mA	1.5	1.9	2.3	V
I <sub>DSS</sub>	drain leakage current	$V_{GS} = 0 \text{ V}; V_{DS} = 28 \text{ V}$	-	-	4.2	μΑ
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	42	50.8	-	Α
I <sub>GSS</sub>	gate leakage current	$V_{GS}$ = 11 V; $V_{DS}$ = 0 V	-	-	420	nΑ
9 <sub>fs</sub>	forward transconductance	$V_{DS}$ = 10 V; $I_{D}$ = 5.25 A	-	18.9	-	S
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $I_D = 5.25 \text{ A}$	-	0.054	-	Ω

## 7. Test information

#### Table 7. Functional test information

Mode of operation: 2-carrier W-CDMA; PAR = 8.4 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1-64 DPCH;  $f_1$  = 2112.5 MHz;  $f_2$  = 2117.5 MHz;  $f_3$  = 2162.5 MHz;  $f_4$  = 2167.5 MHz; RF performance at  $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA;  $T_{case}$  = 25 °C; unless otherwise specified; in a class-AB production test circuit.

Parameter	Conditions	Min	Тур	Max	Unit
average output power		-	55	-	W
power gain	$P_{L(AV)} = 55 W$	16.8	18.5	-	dB
input return loss	$P_{L(AV)} = 55 W$	-	-15	-6	dB
drain efficiency	$P_{L(AV)} = 55 W$	27	31	-	%
adjacent channel power ratio	$P_{L(AV)} = 55 W$	-	-31	-25.5	dBc
	average output power power gain input return loss drain efficiency	average output power $ P_{L(AV)} = 55 \text{ W} $ input return loss $ P_{L(AV)} = 55 \text{ W} $ drain efficiency $ P_{L(AV)} = 55 \text{ W} $	average output power -  power gain $P_{L(AV)} = 55 \text{ W}$ 16.8  input return loss $P_{L(AV)} = 55 \text{ W}$ -  drain efficiency $P_{L(AV)} = 55 \text{ W}$ 27	average output power - 55  power gain $P_{L(AV)} = 55 \text{ W}$ 16.8 18.5  input return loss $P_{L(AV)} = 55 \text{ W}$ 15  drain efficiency $P_{L(AV)} = 55 \text{ W}$ 27 31	average output power - 55 - power gain $P_{L(AV)} = 55 \text{ W}$ 16.8 18.5 - input return loss $P_{L(AV)} = 55 \text{ W}$ 15 -6 drain efficiency $P_{L(AV)} = 55 \text{ W}$ 27 31 -

#### 7.1 Ruggedness in class-AB operation

The BLF7G22L-200 and BLF7G22LS-200 are capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:  $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA;  $P_L$  = 200 W (CW); f = 2110 MHz to 2170 MHz.

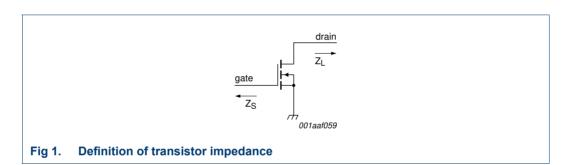
## 7.2 Impedance information

Table 8. Typical impedance

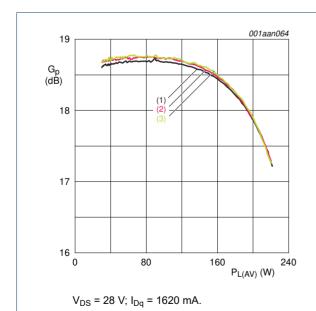
Measured load-pull data;  $I_{Da} = 1620 \text{ mA}$ ;  $V_{DS} = 28 \text{ V}$ .

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]
(MHz)	(Ω)	$(\Omega)$
2050	1.05 – j4.04	2.04 - j1.28
2110	1.18 – j4.17	1.67 – j1.52
2140	1.32 – j4.68	1.67 – j1.52
2170	1.58 – j4.37	1.62 – j1.63
2230	2.55 – j5.14	1.51 – j1.83

[1] Z<sub>S</sub> and Z<sub>L</sub> defined in Figure 1.



## 7.3 1 Tone CW

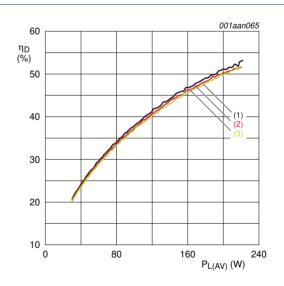


(1) f = 2110 MHz

(2) f = 2140 MHz

(3) f = 2170 MHz

Fig 2. Power gain as a function of average load power; typical values



 $V_{DS} = 28 \text{ V}; I_{Dq} = 1620 \text{ mA}.$ 

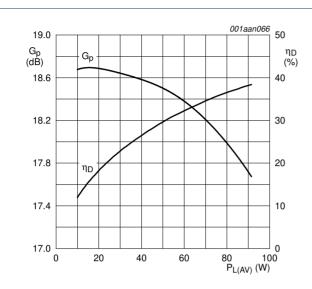
(1) f = 2110 MHz

(2) f = 2140 MHz

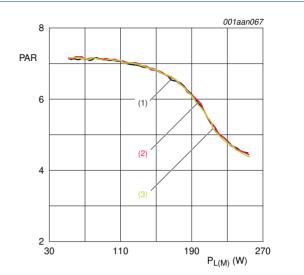
(3) f = 2170 MHz

Fig 3. Drain efficiency as a function of average load power; typical values

#### 7.4 1-carrier W-CDMA



 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; f = 2140 MHz; PAR = 7.2 dB at 0.01 % probability on the CCDF.

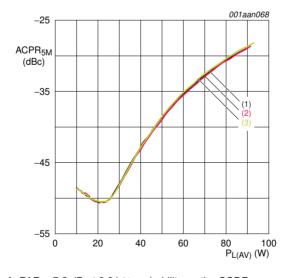


 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; PAR = 7.2 dB at 0.01 % probability on the CCDF.

- (1) f = 2110 MHz
- (2) f = 2140 MHz
- (3) f = 2170 MHz

Fig 4. Power gain and drain efficiency as functions of average load power; typical values



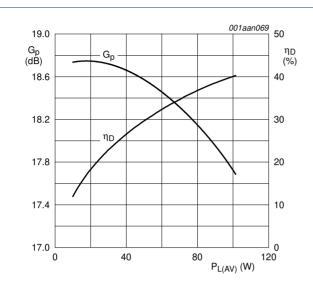


 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; PAR = 7.2 dB at 0.01 % probability on the CCDF.

- (1) f = 2110 MHz
- (2) f = 2140 MHz
- (3) f = 2170 MHz

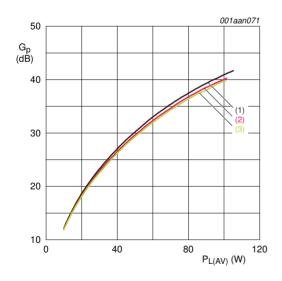
Fig 6. Adjacent power channel ratio (5 MHZ) as function of average load power; typical values

#### 7.5 2-carrier W-CDMA



 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; f = 2140 MHz; Channel Spacing = 5 MHz; PAR = 8.4 dB at 0.01 % probability on the CCDF.

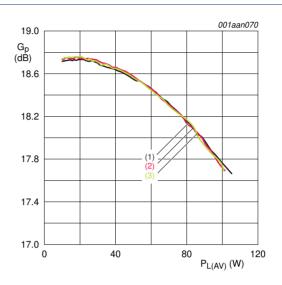
Fig 7. Power gain and drain efficiency as functions of average load power; typical values



 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; Channel Spacing = 5 MHz; PAR = 8.4 dB at 0.01 % probability on the CCDF.

- (1) f = 2110 MHz
- (2) f = 2140 MHz
- (3) f = 2170 MHz

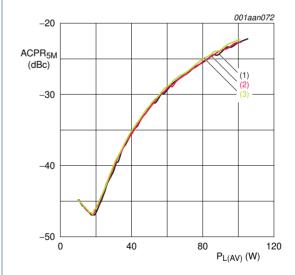
Fig 9. Drain efficiency as function of average load power; typical values



 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; Channel Spacing = 5 MHz; PAR = 8.4 dB at 0.01 % probability on the CCDF.

- (1) f = 2110 MHz
- (2) f = 2140 MHz
- (3) f = 2170 MHz

Fig 8. Power gain as a function of average load power; typical values

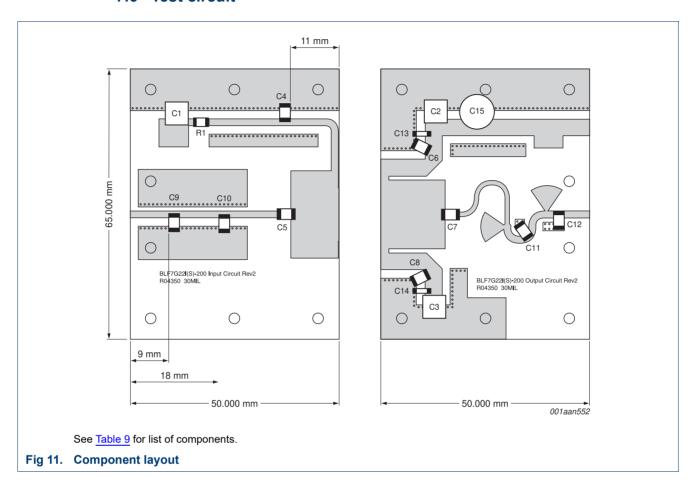


 $V_{DS}$  = 28 V;  $I_{Dq}$  = 1620 mA; Channel Spacing = 5 MHz; PAR = 8.4 dB at 0.01 % probability on the CCDF.

- (1) f = 2110 MHz
- (2) f = 2140 MHz
- (3) f = 2170 MHz

Fig 10. Adjacent power channel ratio (5 MHZ) as function of average load power; typical values

#### 7.6 Test circuit



**Table 9.** List of components
See Figure 11 for component layout.

Component	Description	Value		Remarks
C1	multilayer ceramic chip capacitor	10 μF	[1]	TDK
C2, C3	multilayer ceramic chip capacitor	4.7 μF	[1]	TDK
C4, C5, C6, C7, C8	multilayer ceramic chip capacitor	22 pF	[2]	ATC100B
C9	multilayer ceramic chip capacitor	2.0 pF	[2]	ATC100B
C10	multilayer ceramic chip capacitor	2.1 pF	[2]	ATC100B
C11	multilayer ceramic chip capacitor	0.5 pF	[2]	ATC100B
C12	multilayer ceramic chip capacitor	0.9 pF	[2]	ATC100B
C13, C14	multilayer ceramic chip capacitor	330 nF	[1]	TDK
C15	electrolytic capacitor	470 μF; 63 V		
R1	chip resistor	10 Ω		Philips 1206

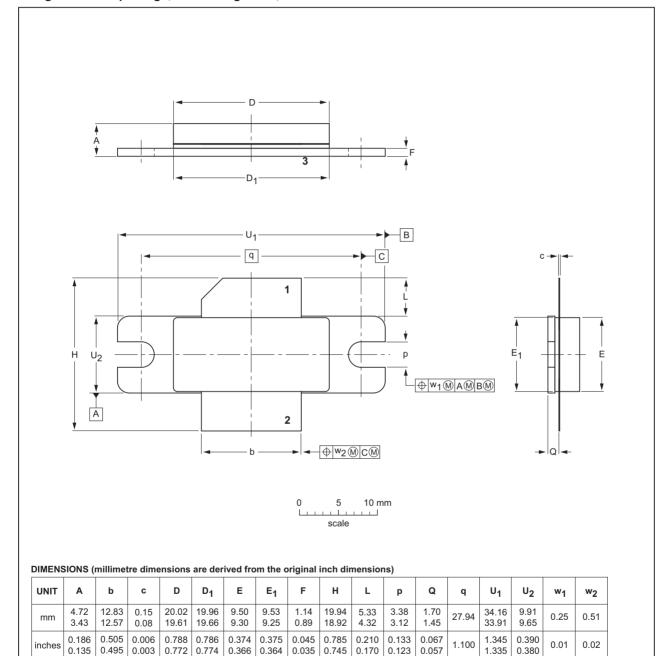
<sup>[1]</sup> TDK or capacitor of same quality.

[2] American Technical Ceramics type 100B or capacitor of same quality.

## 8. Package outline

Flanged ceramic package; 2 mounting holes; 2 leads

SOT502A

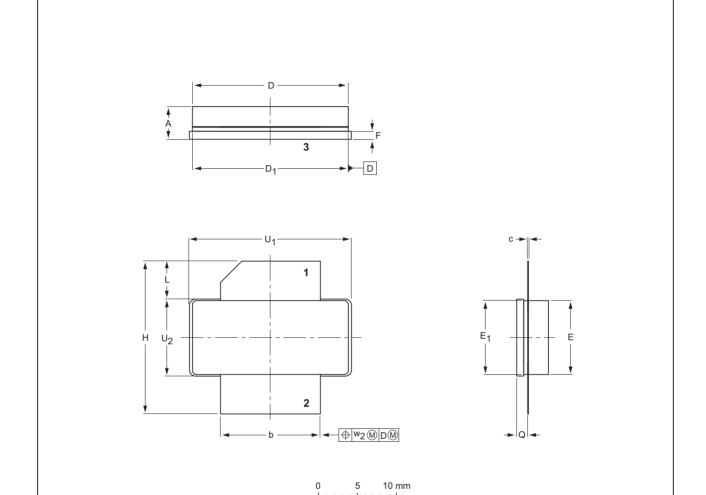


OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT502A					<del>-03-01-10-</del> 12-05-02

Fig 12. Package outline SOT502A

#### Earless flanged ceramic package; 2 leads

SOT502B



#### DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	Α	b	С	D	D <sub>1</sub>	E	E <sub>1</sub>	F	Н	L	Q	U <sub>1</sub>	U <sub>2</sub>	w <sub>2</sub>
mm	4.72 3.43	12.83 12.57	0.15 0.08		19.96 19.66		9.53 9.25	1.14 0.89	19.94 18.92	5.33 4.32	1.70 1.45	20.70 20.45	9.91 9.65	0.25
inches				0.788 0.772										0.010

OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
SOT502B					<del>07-05-09</del> 12-05-02

scale

Fig 13. Package outline SOT502B

## 9. Handling information

#### CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

## 10. Abbreviations

Table 10. Abbreviations

Acronym	Description
3GPP	Third Generation Partnership Project
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
LDMOS	Laterally Diffused Metal Oxide Semiconductor
LDMOST	Laterally Diffused Metal Oxide Semiconductor Transistor
PAR	Peak-to-Average power Ratio
RF	Radio Frequency
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

## 11. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLF7G22L-200_7G22LS-200#5	20150901	Product data sheet	-	BLF7G22L-200_7G22LS-200 v.4
Modifications:	<ul> <li>The format of this document has been redesigned to comply with the new identity guidelines of Ampleon.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> </ul>			
BLF7G22L-200_7G22LS-200 v.4	20110722	Product data sheet	-	BLF7G22L-200_7G22LS-200 v.3
BLF7G22L-200_7G22LS-200 v.3	20110401	Preliminary data sheet	-	BLF7G22L-200_7G22LS-200 v.2
BLF7G22L-200_7G22LS-200 v.2	20101228	Preliminary data sheet	-	BLF7G22L-200_7G22LS-200 v.1
BLF7G22L-200_7G22LS-200 v.1	20100419	Objective data sheet	-	-

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#### 12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
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# BLF7G22L-200; BLF7G22LS-200

**Power LDMOS transistor** 

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# BLF7G22L-200; BLF7G22LS-200

## **AMPLEON**

**Power LDMOS transistor** 

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